

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Yeo et al.)
Serial No.:)
Filed :)
For : **ENHANCED CHIP SCALE PACKAGE**)
FOR WIRE BOND DIES)
Attorney's Docket No.: 4795-002)

Express Mail Certification
Label No. EV016784306US



Raleigh, North Carolina
February 19, 2002

Commissioner for Patents
BOX PATENT APPLICATION
Washington, D.C. 20231

Dear Sir:

CLAIM OF PRIORITY

The applicant in this case claims priority based on a prior application filed in Singapore and identified as Singapore Patent Application No. 200106786-7 filed November 2, 2001.

A certified copy of the Singapore application will be submitted in due course.

Respectfully submitted,

COATS & BENNETT, P.L.L.C.

By:

Larry L. Coats
Registration No. 25,620

Telephone: (919) 854-1844